

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YI-TSUO WU	02/26/2012
RECEIVING PARTY DATA	
Name:	TSMC SOLID STATE LIGHTING LTD.
Street Address:	9, LI-HSIN 4TH RD.
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13399027
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ATTORNEY DOCKET NUMBER:	48047.38
NAME OF SUBMITTER:	DENISE M. WILSON
SIGNATURE:	/Denise M. Wilson/
DATE SIGNED:	03/25/2014
Total Attachments: 2	
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source=48047-38-assign#page2.tif	

ASSIGNMENT

WHEREAS, I

Yi-Tsuo Wu of 6F-2, No. 110, Mingquan Road
Yonghe City, Taipei County, Taiwan, R.O.C.

has invented certain improvements in

**LED PACKAGING STRUCTURE HAVING IMPROVED
THERMAL DISSIPATION AND MECHANICAL STRENGTH**

for which I have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
xx filed on 08/31/2009 and assigned application number 13/399,027; and

WHEREAS, I authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, TSMC Solid State Lighting Ltd., 9, Li-Hsin 4th Rd., HsinChu Science Park, HsinChu, Taiwan, ROC. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC Solid State Lighting Ltd., its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC Solid State Lighting Ltd., its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC Solid State Lighting Ltd., its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC Solid State Lighting Ltd., its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yi-Tsuo Wu

Residence Address: 6F-2, No. 110, Mingquan Road
Yonghe City, Taipei County, Taiwan, R.O.C.

Dated: ✓ 2012/02/26

✓ Yi-Tsuo, Wu
Inventor Signature